PCN Number:	20230612001.1	**PCN Date:**	June 12, 2023
Title:	Qualification of TI Chengdu as an additional Assembly site for select devices		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	Sept 14, 2023	**Sample requests accepted until:**	July 14, 2023*

*Sample requests received after (July 14, 2023) will not be supported.

Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Materials
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing the qualification of TI Chengdu (TI CDAT) as an additional Assembly site for select devices. Material differences between sites are as follows:

Group 1 device:

	TFME	HNA	TI CDAT
Wire type	0.8mil Au	0.8mil Au	0.8mil Cu
Mount Compound	A-09	400194	4226215
Mold compound	R-27	450179	4222198

Group 2 device:

	TFME	HNA	TI CDAT
Wire type	0.8mil Au	0.8mil Au	0.8mil Cu
Mount Compound	A-03	400180	4226215
Mold compound	R-27	450179	4222198

Reason for Change:

Continuity of supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None.

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
TFME	NFM	CHN	Chongchuan Road
Hana Technologies	HNT	THA	Ayutthaya
TI Chengdu	CDA	CHN	Chengdu

Sample product shipping label (not actual product label)

Product Affected Group 1:			
DRV5055A1QDBZR	DRV5055A3QDBZR	DRV5055Z1QDBZR	DRV5055Z3QDBZR
DRV5055A1QDBZT	DRV5055A3QDBZT	DRV5055Z1QDBZT	DRV5055Z3QDBZT
DRV5055A2QDBZR	DRV5055A4QDBZR	DRV5055Z2QDBZR	DRV5055Z4QDBZR
DRV5055A2QDBZT	DRV5055A4QDBZT	DRV5055Z2QDBZT	DRV5055Z4QDBZT
Product Affected Group 2:			
DRV5056A1QDBZR	DRV5056A6QDBZT	DRV5057A1QDBZR	DRV5057Z1QDBZT
DRV5056A1QDBZT	DRV5056Z1QDBZR	DRV5057A1QDBZT	DRV5057Z2QDBZR
DRV5056A2QDBZR	DRV5056Z1QDBZT	DRV5057A2QDBZR	DRV5057Z2QDBZT
DRV5056A2QDBZT	DRV5056Z2QDBZR	DRV5057A2QDBZT	DRV5057Z3QDBZR
DRV5056A3QDBZR	DRV5056Z2QDBZT	DRV5057A3QDBZR	DRV5057Z3QDBZT
DRV5056A3QDBZT	DRV5056Z3QDBZR	DRV5057A3QDBZT	DRV5057Z4QDBZR
DRV5056A4QDBZR	DRV5056Z3QDBZT	DRV5057A4QDBZR	DRV5057Z4QDBZT
DRV5056A4QDBZT	DRV5056Z4QDBZR	DRV5057A4QDBZT	
DRV5056A6QDBZR	DRV5056Z4QDBZT	DRV5057Z1QDBZR	

Qualification Report

Approve Date 05-JUNE-2023

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: DRV5055A1QDBZR	Qual Device: DRV5056A1QDBZR	Qual Device: DRV5057A1QDBZR	QBS Reference: SN74HCS595QDYYRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	1/77/0	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/15/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/15/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	1/22/0	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	3/30/0
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	-

ESD	E2	ESD CDM	-	500 Volts	-	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	-	1/6/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	3/90/0

QBS: Qual By Similarity
Qual Device DRV5055A1QDBZR is qualified at MSL1 260C
Qual Device DRV5056A1QDBZR is qualified at MSL1 260C
Qual Device DRV5057A1QDBZR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours , 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.